



# 제 30회 한국반도체학술대회

The 30th Korean Conference on Semiconductors

2023년 2월 13일(월) ~ 15일(수) | 강원도 하이원리조트(그랜드호텔 컨벤션타워)

2023년 2월 14일(화), 09:00-10:45

Room C (사파이어 I, 5층)

## A. Interconnect & Package 분과

### [TC1-A] Emerging Interconnect

좌장: 김병준 교수(한국공학대학교), 정성엽 박사(삼성전자)

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| TC1-A-1<br>09:00-09:15         | <b>NiAl Metallization for Advanced Interconnects</b><br>Kyeong-Youn Song <sup>1</sup> , Seungjun Na <sup>2</sup> , and Hoo-Jeong Lee <sup>1,2</sup><br><sup>1</sup> SKKU Advanced Institute of Nano Technology, Sungkyunkwan University, <sup>2</sup> Department of Smart Fab. Technology, Sungkyunkwan University                                                                       |
| TC1-A-2<br>09:15-09:30         | <b>확산방지층 두께 및 열처리에 따른 Ru 배선의 계면신뢰성 평가 및 분석</b><br>정대윤 <sup>1</sup> , 권우빈 <sup>1</sup> , 김윤혜 <sup>2</sup> , Yohei Kotsugi <sup>3</sup> , 김가희 <sup>1</sup> , 김수현 <sup>4</sup> , 박영배 <sup>1</sup><br><sup>1</sup> 안동대학교 신소재공학부 청정에너지 소재기술연구센터, <sup>2</sup> 영남대학교 신소재공학부, <sup>3</sup> Chemical Materials Development Department, TANAKA Precious Metals, <sup>4</sup> 울산과학기술원 반도체 소재부품 대학원 |
| TC1-A-3<br>09:30-09:45         | <b>Growth Study of Amorphous Carbon (a-C) Atomic Layer Deposition (ALD) for Memory Electrode Application</b><br>Tae Hyun Kim <sup>1</sup> , Myoungsub Kim <sup>2</sup> , Seungwon Park <sup>1</sup> , Seung-min Chung <sup>1</sup> , and Hyungjun Kim <sup>1</sup><br><sup>1</sup> School of Electrical and Electronic Engineering, Yonsei University, <sup>2</sup> SK Hynix             |
| TC1-A-4<br>09:45-10:00         | <b>Deep Learning Segmentation Modeling for SiN, SiO<sub>2</sub> Film Deposition Process Defect of HBM</b><br>Intae Whoang, Jin Hee Hong, Dong Hee Son, and Jin Pyung Kim<br>SK Hynix                                                                                                                                                                                                     |
| TC1-A-5<br>10:00-10:15         | <b>Highly Enhanced ALD TaN Barrier for Advanced BEOL Manufacturing</b><br>Junki Jang, Changhyun Kim, Yunki Choi, Jeonghoon Ahn, and Jahum Ku<br>Foundry Business, Samsung Electronics Co., Ltd.                                                                                                                                                                                          |
| TC1-A-6<br>10:15-10:45<br>[초청] | <b>Process Window of Interconnection Materials for Semiconductor and Display Applications</b><br>Yong-Sung Eom, Gwang-Mun Choi, Jiho Joo, Ki-Seok Jang, Jin-Heuk Oh, Chanmi Lee, In-Seok Kye, Yoon-Hwan Moon, Seok-Hwan Moon, and Kwang-Seong Choi<br>ETRI                                                                                                                               |